

IN THE CLAIMS:

Please substitute the following claims for the same-numbered claims in the application:

1-7. (Cancelled).

8. (Currently Amended) A method for testing integrated circuit devices after manufacture, said method comprising:

testing an initial group of devices to produce an initial failing group of devices that failed said testing of said initial group, wherein said devices in said initial failing group are identified by type of failure;

retesting all said devices in said initial failing group to identify a retested passing group of devices that passed said retesting;

analyzing said devices in said retested passing group to produce statistics regarding the likelihood that a failing device will pass said retesting according to said type of failure;

evaluating said statistics to determine which types of failures have retest passing rates above a predetermined threshold to produce a listing of types of defects approved for retesting;

testing an additional group of devices that is different from said initial group of devices to produce an additional failing group of devices that failed said testing of said additional ~~groups~~ group; and

retesting only devices in said additional failing group that have one of said types of defects approved for retesting.

9. (Original) The method in claim 8, further comprising adding types of defects associated with testing errors to said types of defects approved for retesting.
10. (Original) The method in claim 8, wherein said testing processes comprise probe type testing.
11. (Original) The method in claim 8, wherein said devices comprise integrated circuit chips.
12. (Original) The method in claim 8, wherein said evaluating process optimizes said retesting of said additional groups.
13. (Original) The method in claim 8, wherein a listing of said types of defects approved for retesting comprises an optimized retest table.
14. (Original) The method in claim 8, wherein said initial group of devices and said additional groups of devices comprise the same type of device.
15. (Currently Amended) A method for testing integrated circuit devices after manufacture, said method comprising:

testing an initial group of devices to produce an initial failing group of devices that failed said testing of said initial group, wherein said devices in said initial failing group are identified

by type of failure;

retesting said devices in said initial failing group to identify a retested passing group of devices that passed said retesting;

analyzing said devices in said retested passing group to produce statistics regarding the likelihood that a failing device will pass said retesting according to said type of failure;

evaluating said statistics to determine which types of failures have retest passing rates above a predetermined threshold to produce a listing of types of defects approved for retesting;

testing an additional group of devices that is different from said initial group of devices to produce an additional failing group of devices that failed said testing of said additional ~~groups~~ group;

identifying types of devices having a predetermined reduced demand; and

retesting only devices in said additional failing ~~groups~~ group that have one of said types of defects approved for retesting and that are not said types of devices for which there is said predetermined reduced demand.

16. (Original) The method in claim 15, further comprising adding types of defects associated with testing errors to said types of defects approved for retesting.

17. (Original) The method in claim 15, wherein said testing processes comprise probe type testing.

18. (Original) The method in claim 15, wherein said devices comprise integrated circuit

chips.

19. (Original) The method in claim 15, wherein said evaluating process optimizes said retesting of said additional groups.

20. (Original) The method in claim 15, wherein a listing of said types of defects approved for retesting comprises an optimized retest table.

21. (Original) The method in claim 15, wherein said initial group of devices and said additional groups of devices comprise the same type of device.

22-28. (Cancelled).

29. (Currently Amended) A system for testing integrated circuit devices after manufacture, said system comprising:

means for testing an initial group of devices to produce an initial failing group of devices, wherein said devices in said initial failing group are identified by type of failure;

means for retesting said devices in said initial failing group to identify a retested passing group of devices;

means for analyzing said devices in said retested passing group to produce statistics regarding the likelihood that a failing device will pass said retesting according to said type of failure; and

means for evaluating said statistics to determine which types of failures have retest passing rates above a predetermined threshold to produce a listing of types of defects approved for retesting;

means for testing an additional group of devices that is different from said initial group of devices to produce an additional failing group of devices; and

means for retesting only devices in said additional failing group that have one of said types of defects approved for retesting.

30-36. (Cancelled).